

Title (en)  
RELAY MODULE

Title (de)  
RELAISMODUL

Title (fr)  
MODULE RELAIS

Publication  
**EP 3850652 A1 20210721 (DE)**

Application  
**EP 19758413 A 20190826**

Priority  
• BE 201805624 A 20180912  
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Abstract (en)  
[origin: WO2020052947A1] The invention relates to an electromagnetic relay module (100) comprising a first circuit branch (119) having a first capacitor (115) and a first relay (103) connected in series with the first capacitor (115), a second circuit branch (121) having a second capacitor (117) and a second relay (105) connected in series with the second capacitor (117), and a switch element (125) arranged between the first circuit branch (119) and the second circuit branch (121) and having a first switch status and a second switch status. In the first switch status of the switch element (125), the first circuit branch (119) and the second circuit branch (121) are connected in parallel. In the second switch status of the switch element (125), the first relay (103) and the second relay (105) are connected in series. When the relay module (100) is switched on, the switch element (125) is designed to switch from the first switch status into the second switch status in order to increase the total resistance of the relay module (100).

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**H01H 3/022** (2013.01 - US); **H01H 47/005** (2013.01 - US); **H01H 47/04** (2013.01 - EP US); **H01H 47/226** (2013.01 - US);  
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Citation (search report)  
See references of WO 2020052947A1

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Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
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